

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Application of:

U.S. Patent No. 6,455,348

Serial No.: 09/521,670

Issued: September 24, 2002

Inventor: Yukio YAMAGUCHI

Group Art Unit: 2825

Examiner: G. LEE

For: LEAD FRAME, RESIN-MOLDED SEMICONDUCTOR DEVICE, AND METHOD
FOR MANUFACTURING THE SAME

DECLARATION PURSUANT TO 37 C.F.R. § 1.175(a)

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

I declare:

THE INVENTORS

1. That I, Yukio Yamaguchi, reside at the address listed below, and declare that I am a citizen of Japan; that I am employed by Matsushita Electric Industrial Co., Ltd. of Osaka Japan; that Matsushita is the Assignee of the entire interest of the above-identified patent; that at the time the application for the above-identified Patent was filed I was engaged in the design of lead frames and resin-molded semiconductor devices as described in United States Letters Patent No. 6,455,348 ("original patent"), that I do not know and do not believe that the invention was ever known or used in the United States before my invention; and that I am the declarant, applicant

and patentee, referred to hereinafter.

2. That I believe the original patent to be wholly or partly inoperative or invalid, by reason of my claiming less than I had a right to claim.

3. That I believe that the error regarding my narrow claiming of the invention arose inadvertently and without deceptive intent.

4. In accordance with 35 U.S.C. § 120, I claim the benefit of the filing date of prior US application Serial No. 09/244,074 (the '074 application), filed on February 4, 1999, which is now USP No. 6,081,029, and in accordance with 35 U.S.C. § 119, I claim the benefit of a foreign filing date on the basis of Japanese Patent Application No. 10-060811, filed on March 8, 2000. A certified copy of Japanese priority document was filed in the '074 application that issued as U.S. Patent No. 6,081,029.

5. That I hereby state that I have reviewed and understand the contents of the above-identified reissue application, including the addition of newly added claims 9-15.

6. That I acknowledge the duty to disclose information of which I am aware which is material to the examination of the application for the above-identified reissue application in accordance with 37 C.F.R. § 1.56(a).

I declare further that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any

patent issuing thereon.

Date: January 8, 2004

Yukio Yamaguchi: YUKIO YAMAGUCHI

Address: 2-8-9 KUROZU OTSU
SIGA JAPAN

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ASSENT OF ASSIGNEE TO REISSUE

Hon. Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The undersigned, by authority vested in him by Matsushita Electric Industrial, Co., Ltd., assignee of the entire interest in the above-identified Letters Patent, the invention described therein, and in any reissue thereof by assignment recorded at Reel 9753, Frame 0250, hereby assents on behalf of the assignee to the accompanying reissue application.

I hereby declare that I have been empowered with the authority to consent to the above-identified reissue application and sign this document on behalf of Matsushita Electric Industrial, Co. LTD.

Director, IP Development Center,

Date: _____

Title: Authorized Signing Officer

Name: Isamu Shimura

Signature: 